

# Schottky Barrier Diode NSR20F20NXT5G

These Schottky barrier diodes are optimized for low forward voltage drop and low leakage current and are offered in a Chip Scale Package (CSP) to reduce board space. The low thermal resistance enables designers to meet the challenging task of achieving higher efficiency and meeting reduced space requirements.

### **Features**

- Low Forward Voltage Drop 450 mV @ 2.0 A
- Low Reverse Current 30 μA @ 10 V VR
- 2.0 A of Continuous Forward Current
- Power Dissipation of 665 mW with Minimum Trace
- ESD Rating Human Body Model: Class 3B
  - Machine Model: Class C
- High Switching Speed
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

# **Typical Applications**

- LCD and Keypad Backlighting
- Camera Photo Flash
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

# Markets

- Mobile Handsets
- MP3 Players
- Digital Camera and Camcorders
- Notebook PCs & PDAs
- GPS

# **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Reverse Voltage	$V_{R}$	20	V
Forward Current (DC)	I <sub>F</sub>	2.0	Α
Forward Surge Current (60 Hz @ 1 cycle)	I <sub>FSM</sub>	28	Α
Repetitive Peak Forward Current (Pulse Wave = 1 sec, Duty Cycle = 66%)	I <sub>FRM</sub>	4.0	Α
ESD Rating: Human Body Model Machine Model	ESD	> 8 > 400	kV V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

# 20 V SCHOTTKY BARRIER DIODE





CASE 152AB

# MARKING DIAGRAM



LT = Specific Device Code
M = Month Code

#### ORDERING INFORMATION

Device	Package	Shipping†
NSR20F20NXT5G	DSN2 (Pb-Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# NSR20F20NXT5G

# THERMAL CHARACTERISTICS

Characteristic	Symbol	Min	Тур	Max	Unit
Thermal Resistance Junction-to-Ambient (Note 1) Total Power Dissipation @ T <sub>A</sub> = 25°C	R <sub>θJA</sub> P <sub>D</sub>			213 586	°C/W mW
Thermal Resistance Junction-to-Ambient (Note 2) Total Power Dissipation @ T <sub>A</sub> = 25°C	R <sub>0JA</sub> P <sub>D</sub>			80 1.56	°C/W W
Storage Temperature Range	T <sub>stg</sub>			-40 to +125	°C
Junction Temperature	TJ			+150	°C

- Mounted onto a 4 in square FR-4 board 50 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.
   Mounted onto a 4 in square FR-4 board 1 in sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.

# **ELECTRICAL CHARACTERISTICS** ( $T_A = 25$ °C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Leakage (V <sub>R</sub> = 10 V) (V <sub>R</sub> = 20 V)	I <sub>R</sub>			30 150	μΑ
Forward Voltage (I <sub>F</sub> = 1.0 A) (I <sub>F</sub> = 2.0 A)	V <sub>F</sub>		0.390 0.450	0.420 0.470	V
Reverse Recovery Time $(I_F = I_R = 10 \text{ mA}, I_{R(REC)} = 1.0 \text{ mA}, Figure 4)$	t <sub>rr</sub>		80		ns

# NSR20F20NXT5G

# **TYPICAL CHARACTERISTICS**

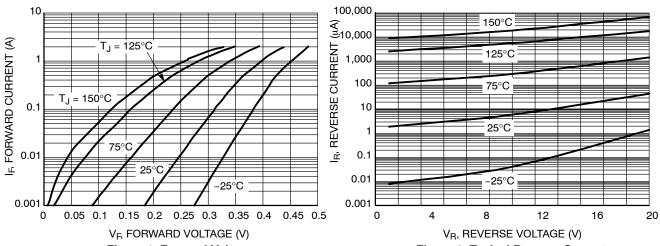


Figure 1. Forward Voltage

Figure 2. Typical Reverse Current

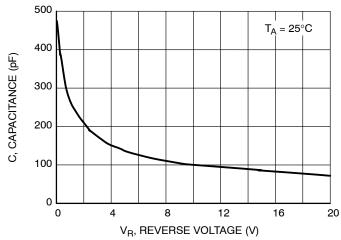
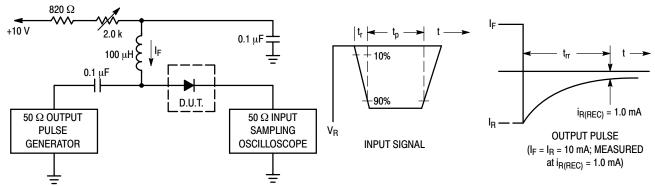


Figure 3. Typical Capacitance



Notes: 1. A 2.0 k $\Omega$  variable resistor adjusted for a Forward Current (I<sub>F</sub>) of 10 mA.

2. Input pulse is adjusted so  $I_{R(peak)}$  is equal to 10 mA.

3.  $t_p * t_{rr}$ 

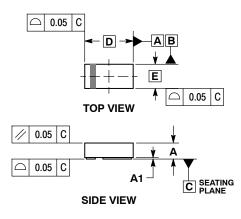
Figure 4. Recovery Time Equivalent Test Circuit

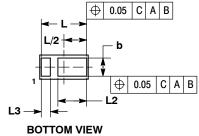




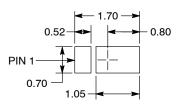
DSN2, 1.6x0.8, 0.9P, (0603) CASE 152AB ISSUE C

**DATE 30 APR 2017** 





# **MOUNTING FOOTPRINT\***



**DIMENSIONS: MILLIMETERS** 

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

See Application Note AND8464/D for more mounting details

- NOTES:
  1. DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.

	MILLIMETERS			
DIM	MIN MAX			
Α	0.25	0.31		
A1		0.05		
b	0.55	0.65		
D	1.60 BSC			
Е	0.80 BSC			
L	1.45	1.55		
2	0.90	1.00		
L3	0.25	0.35		

# **GENERIC MARKING DIAGRAM1\***



XXXX = Specific Device Code YYY = Year Code

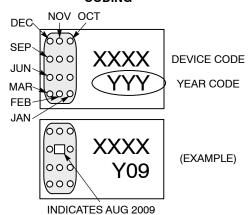
# **GENERIC MARKING DIAGRAM2\***



XX = Specific Device Code M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

# **CATHODE BAND MONTH CODING**



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DESCRIPTION:	DSN2, 1.6X0.8, 0.9P, (0603)		PAGE 1 OF 1	

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